

## Special Issue

# Smart Materials from Biomedicine to Construction

### Message from the Guest Editors

This Special Issue will cover original experimental and applied research on smart materials (e.g., chemoresponsive, polymers, self-healing, shape memory, magnetostrictive, piezoelectric, and ferroelectric) with practical applications. The scope covers smart materials for a range of disciplines and industries from biomedical to energy, automotive, electronics, advanced manufacturing, aerospace, marine, and construction. It is my pleasure to invite you to submit a manuscript for this Special Issue. Manuscripts will be welcomed from both academic researchers and authors from industry involved in the field.

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### Guest Editors

Dr. Shima Taheri

Dr. M. Asun Cantera

Dr. Lucian Pîslaru-Dănescu

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### Deadline for manuscript submissions

closed (31 May 2021)



## Applied Sciences

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## About the Journal

### Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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### Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo  
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